

SOT1991-3(SC)

HTQFN24, thermal enhanced thin quad flat package; no leads; step-cut wettable flank; 24 terminals, 0.5 mm pitch, 4 mm x 4 mm x 1 mm body

23 January 2019

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HTQFN24
Package style descriptive code	HTQFN (thermal enhanced thin quad flatpack; no leads)
Mounting method type	S (surface mount)
Issue date	15-01-2019
Manufacturer package code	98ASA01384D

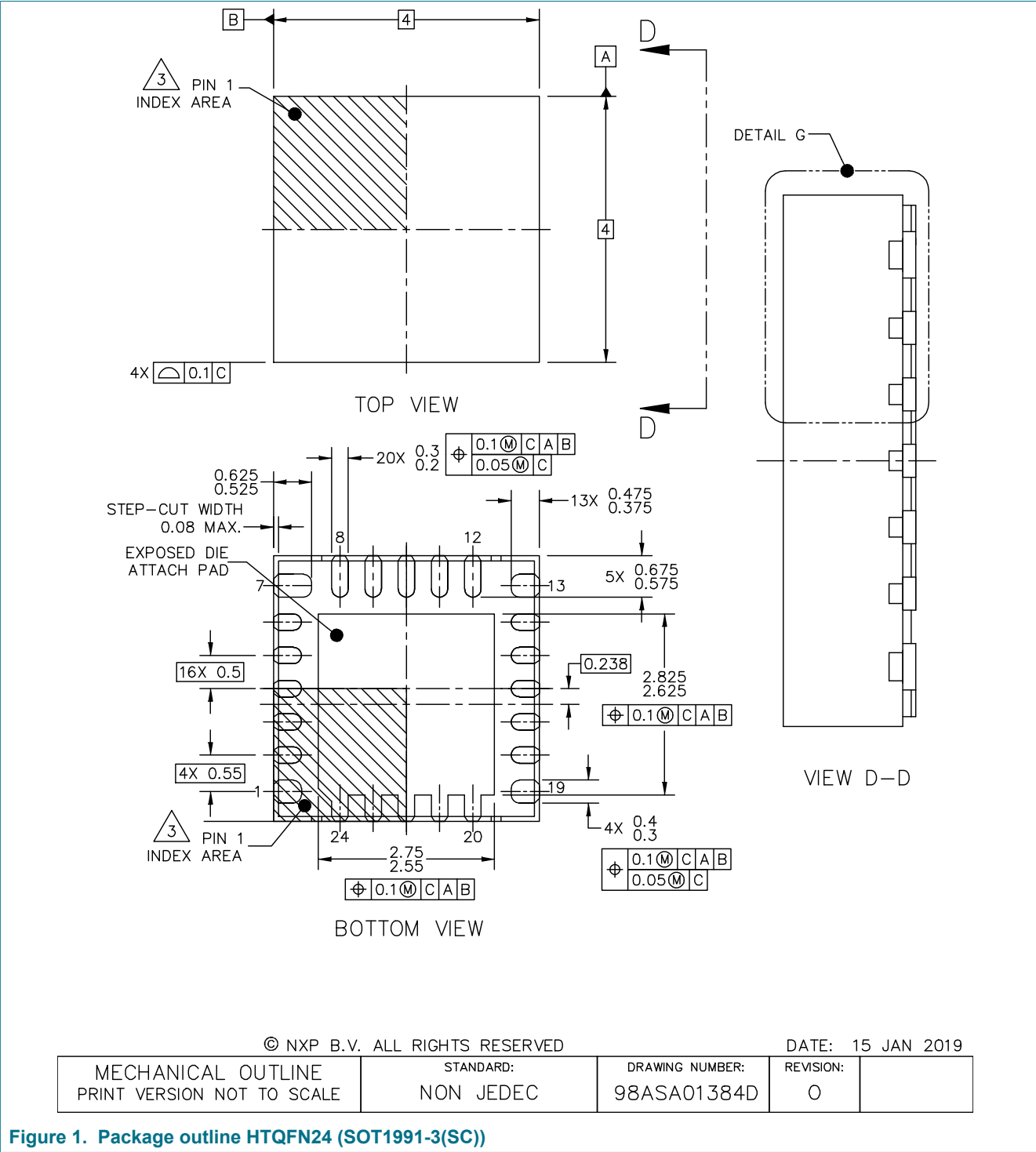
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	4	-	mm
package width	-	4	-	mm
seated height	-	1	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	24	-	

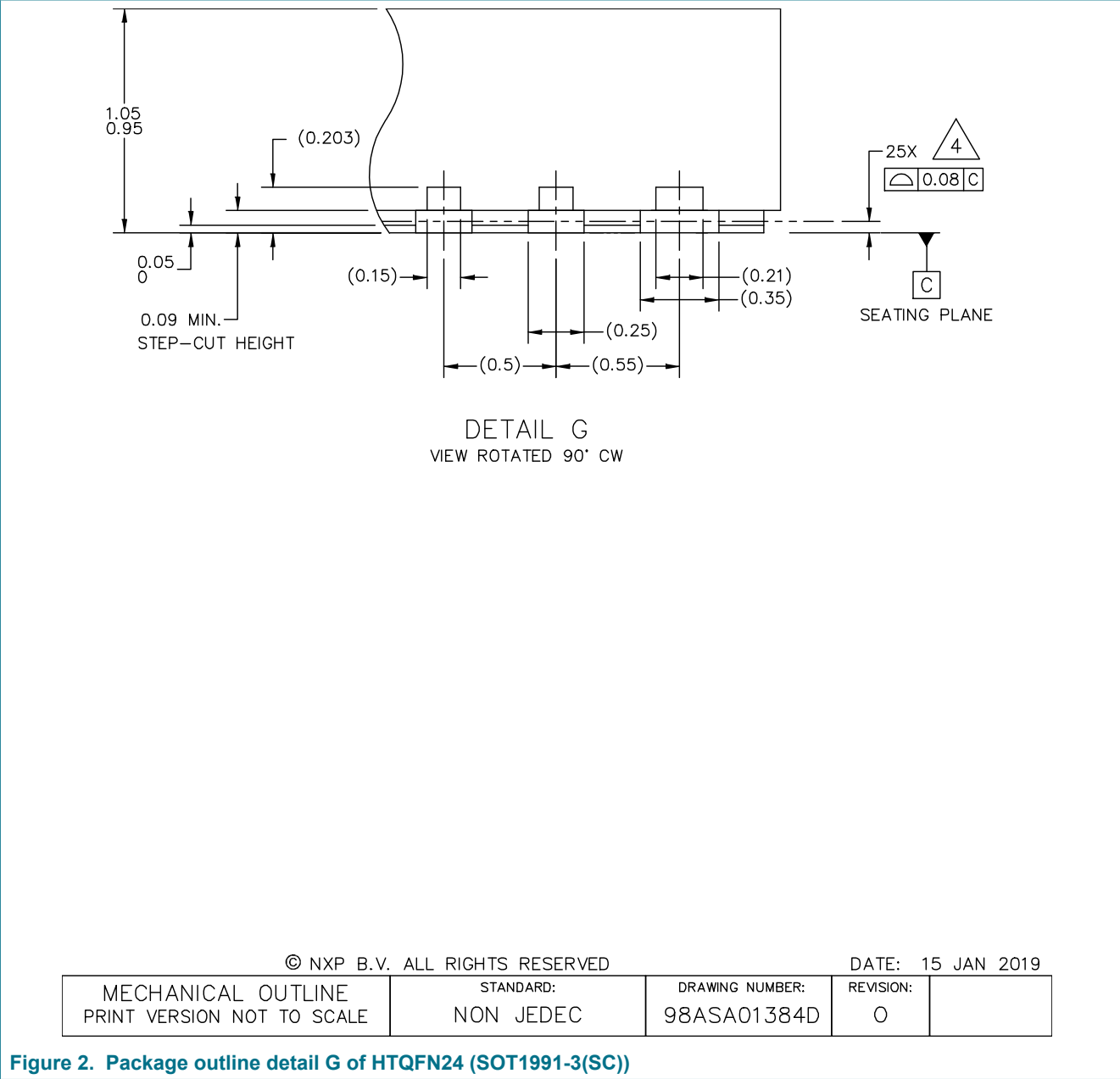


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2 Package outline

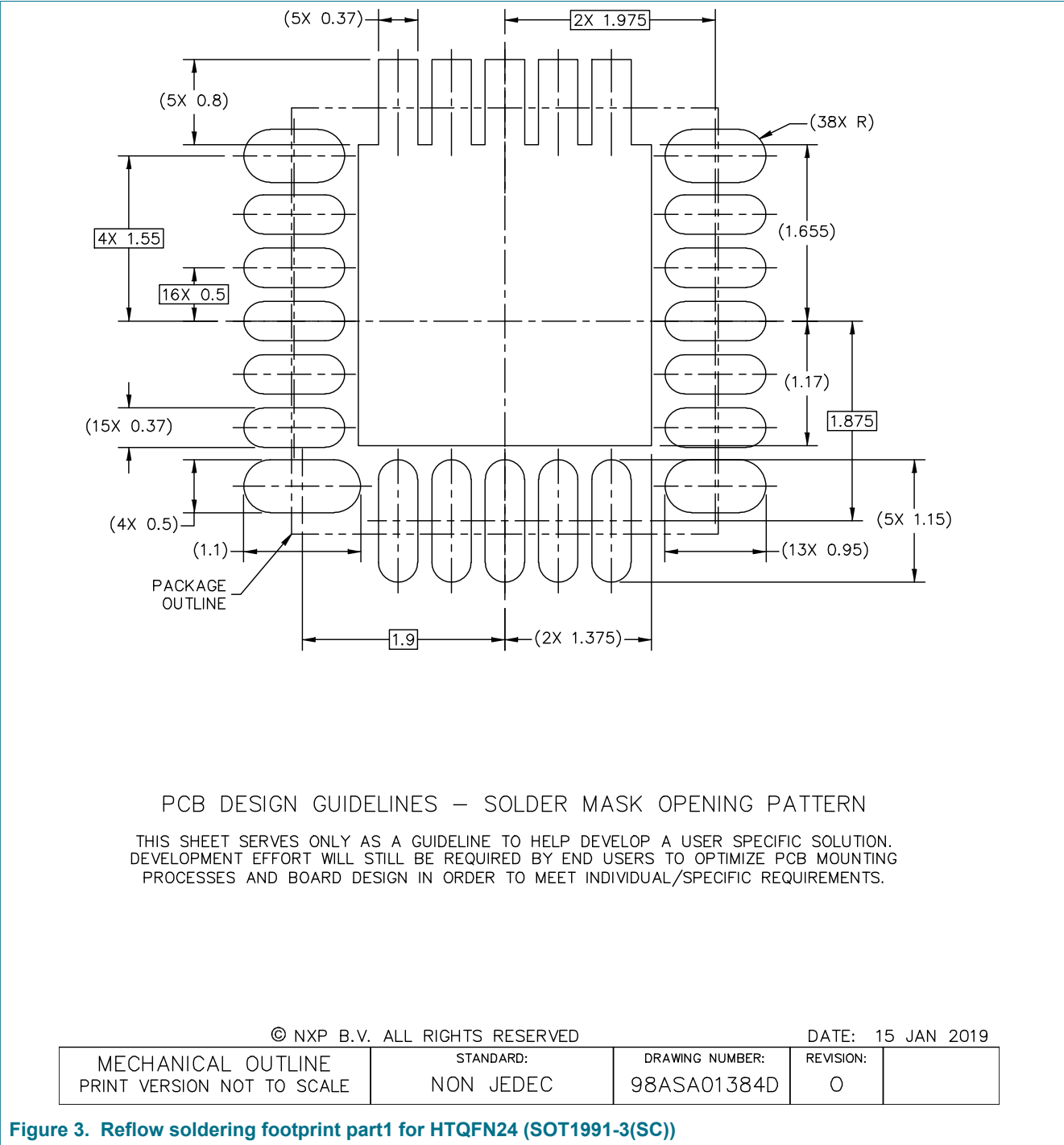


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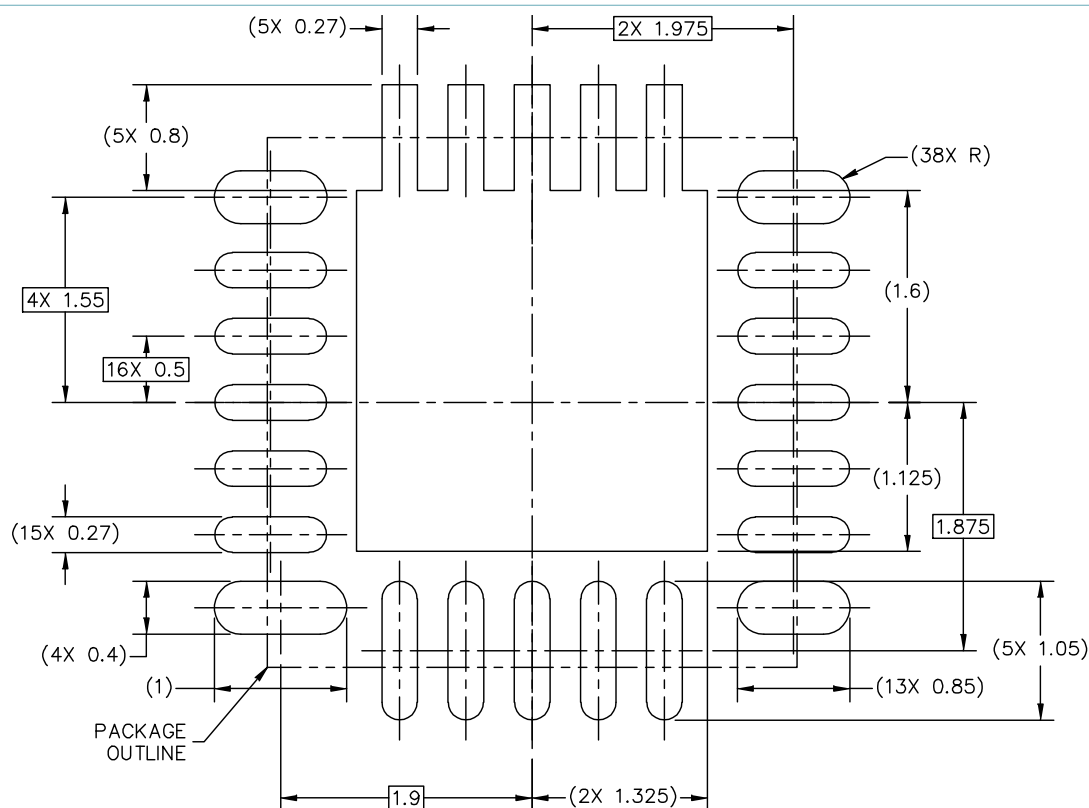


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3 Soldering



HTQFN24, thermal enhanced thin quad flat package; no leads; step-cut wettable flank; 24 terminals, 0.5 mm pitch, 4 mm x 4 mm x 1 mm body



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING
PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

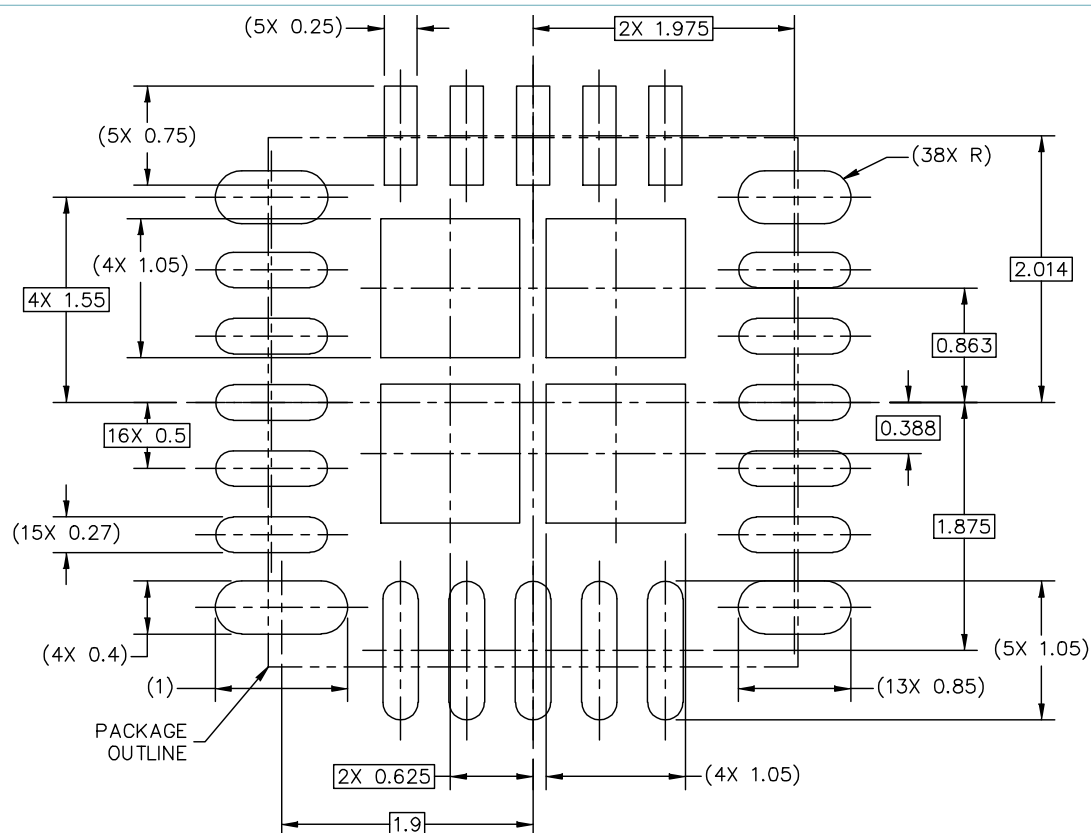
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MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01384D	REVISION: 0
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Figure 4. Reflow soldering footprint part2 for HTQFN24 (SOT1991-3(SC))

HTQFN24, thermal enhanced thin quad flat package; no leads; step-cut wettable flank; 24 terminals, 0.5 mm pitch, 4 mm x 4 mm x 1 mm body



RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 5. Reflow soldering footprint part3 for HTQFN24 (SOT1991-3(SC))

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- NOTES:
- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
 - 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
 - 3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
 - 4. COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG AND CORNER NON–FUNCTIONAL PADS.
 - 5. MIN. METAL GAP SHOULD BE 0.25 MM.

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Figure 6. Package outline note of HTQFN24 (SOT1991-3(SC))

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4 Legal information

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